



SSC8040GN4

N-Channel Enhancement Mode MOSFET

➤ Features

V_{DS}	V_{GS}	$R_{DS(ON)}$ Typ.	I_D
40V	$\pm 20V$	21m Ω @10V	27A
		25m Ω @4V5	

➤ Description

This device is N-Channel enhancement MOSFET. Uses advanced trench technology and design to provide excellent RDSON with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit.

100% UIS + ΔV_{DS} + R_g Tested!

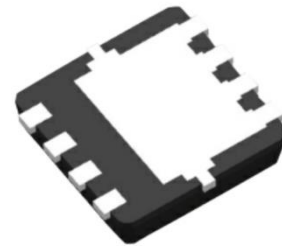
➤ Applications

- Motor Drive Control
- DCDC Conversion
- Power Supplies
- Synchronous Rectification

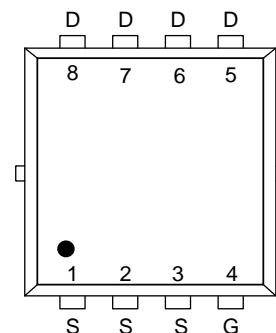
➤ Ordering Information

Device	Package	Shipping
SSC8040GN4	PDFN3.3X3.3-8L	5000/Reel

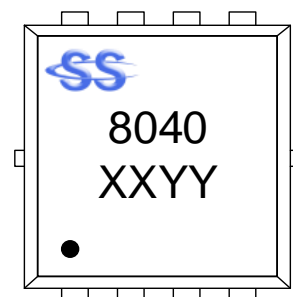
➤ Pin Configuration



PDFN3.3X3.3-8L (Bottom View)



Pin Configuration



Marking

(XXYY: Internal Traceability Code)

**➤ Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

Symbol	Parameter		Ratings	Unit
V_{DSS}	Drain-to-Source Voltage		40	V
V_{GSS}	Gate-to-Source Voltage		± 20	V
I_{D}	Continuous Drain Current ^d	$T_{\text{C}}=25^{\circ}\text{C}$	27	A
		$T_{\text{C}}=100^{\circ}\text{C}$	14.7	
I_{DSM}	Continuous Drain Current ^a	$T_{\text{A}}=25^{\circ}\text{C}$	9.8	A
		$T_{\text{A}}=70^{\circ}\text{C}$	6.9	
I_{DM}	Pulsed Drain Current ^b		109	A
P_{D}	Power Dissipation ^c	$T_{\text{C}}=25^{\circ}\text{C}$	25	W
		$T_{\text{C}}=100^{\circ}\text{C}$	10	
P_{DSM}	Power Dissipation ^a	$T_{\text{A}}=25^{\circ}\text{C}$	3.2	W
		$T_{\text{A}}=70^{\circ}\text{C}$	2.05	
I_{AS}	Avalanche Current ^b $L=0.5\text{mH}$ Single Pulse		8	A
E_{AS}	Avalanche Energy ^b $L=0.5\text{mH}$ Single Pulse		16	mJ
T_{J}	Operation junction temperature		-55~150	$^{\circ}\text{C}$
T_{STG}	Storage temperature range		-55~150	

➤ Thermal Resistance Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Unit
$R_{\theta\text{JA}}$	Junction-to-Ambient Thermal Resistance ^a	39	$^{\circ}\text{C}/\text{W}$
$R_{\theta\text{JC}}$	Junction-to-Case Thermal Resistance	5	

Note:

- The value of $R_{\theta\text{JA}}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with $T_{\text{A}}=25^{\circ}\text{C}$. The value in any given application depends on the user is specific board design. The power dissipation is based on the $t \leq 10\text{s}$ thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation P_{D} is based on $T_{\text{J}(\text{MAX})}=150^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- The maximum current rating is package limited.

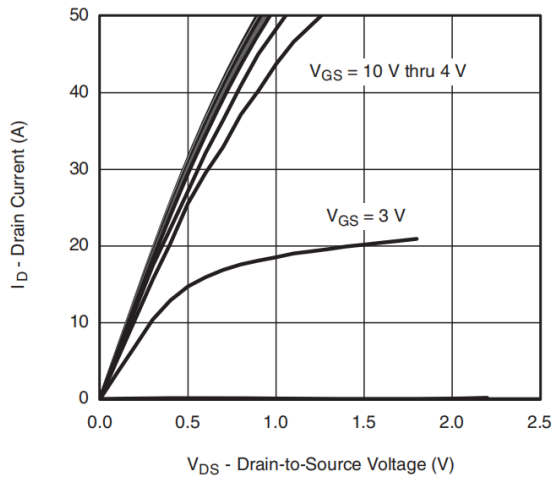


➤ **Electrical Characteristics (T_A=25°C unless otherwise noted)**

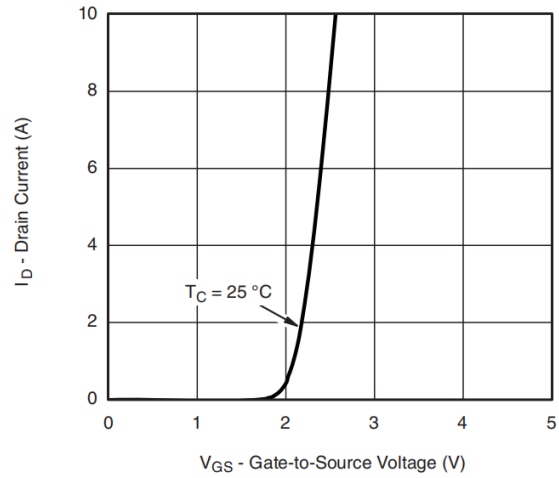
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250uA	40			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250uA	1	1.5	2.5	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 9A		21	27	mΩ
		V _{GS} = 4.5V, I _D = 6A		25	35	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40V, V _{GS} = 0V			1	uA
Gate-Source Leak Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
Transconductance	G _{FS}	V _{DS} = 5V, I _D = 6A		9.2		s
Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 6A		0.8	1.3	V
Input Capacitance	C _{ISS}	V _{DS} = 20V, V _{GS} = 0V, f = 1MHz		530		pF
Output Capacitance	C _{OSS}			68		
Reverse Transfer Capacitance	C _{RSS}			58		
Total Gate Charge	Q _G	V _{GS} = 10V, V _{DS} = 20V, I _D = 5A		13.5		nC
Gate to Source Charge	Q _{GS}			1.7		
Gate to Drain Charge	Q _{GD}			2.2		
Turn-on Delay Time	T _{D(ON)}	V _{GS} = 10V, V _{DS} = 20V, I _D = 5A, R _G = 3Ω		11		ns
Rise Time	T _r			9		
Turn-off Delay Time	T _{D(OFF)}			15		
Fall Time	T _f			10		
Diode Recovery Time	T _{rr}	I _F =10A, di/dt=100A/us		17		ns
Diode Recovery Charge	Q _{rr}	I _F =10A, di/dt=100A/us		8.5		nC



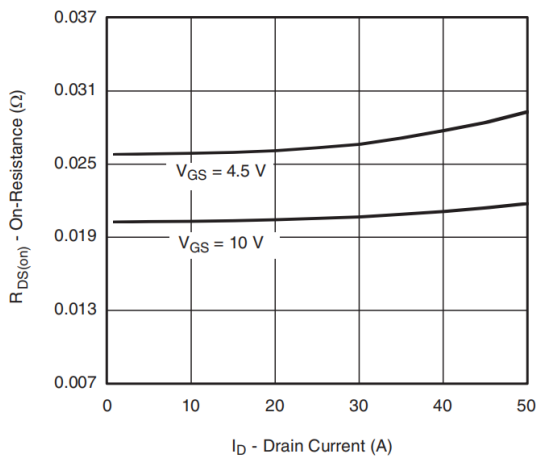
➤ Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)



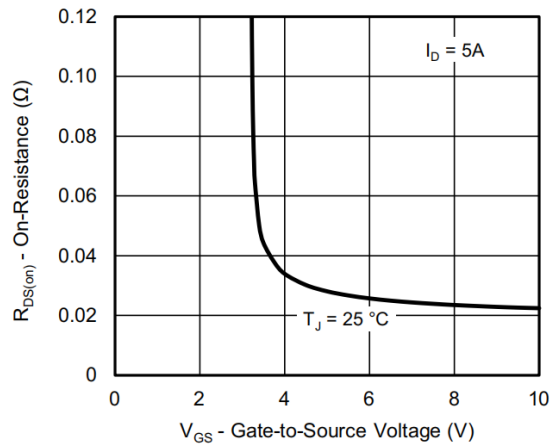
Output Characteristics



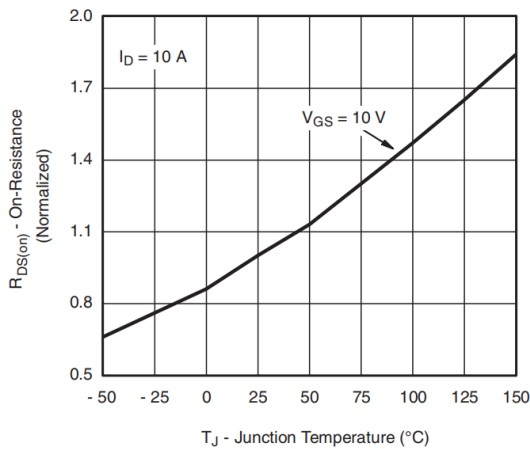
Transfer Characteristics



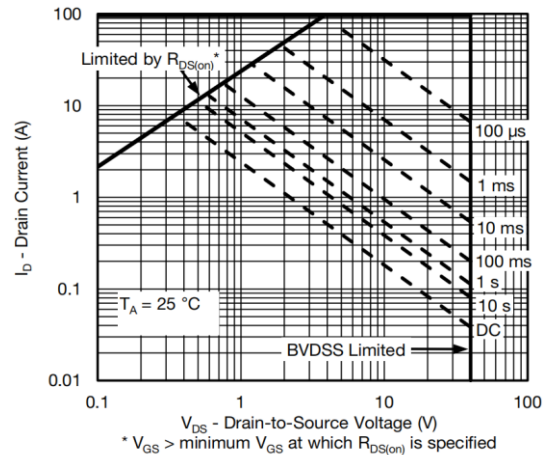
On-Resistance vs. Drain Current and Gate Voltage



On-Resistance vs. Gate-to-Source Voltage

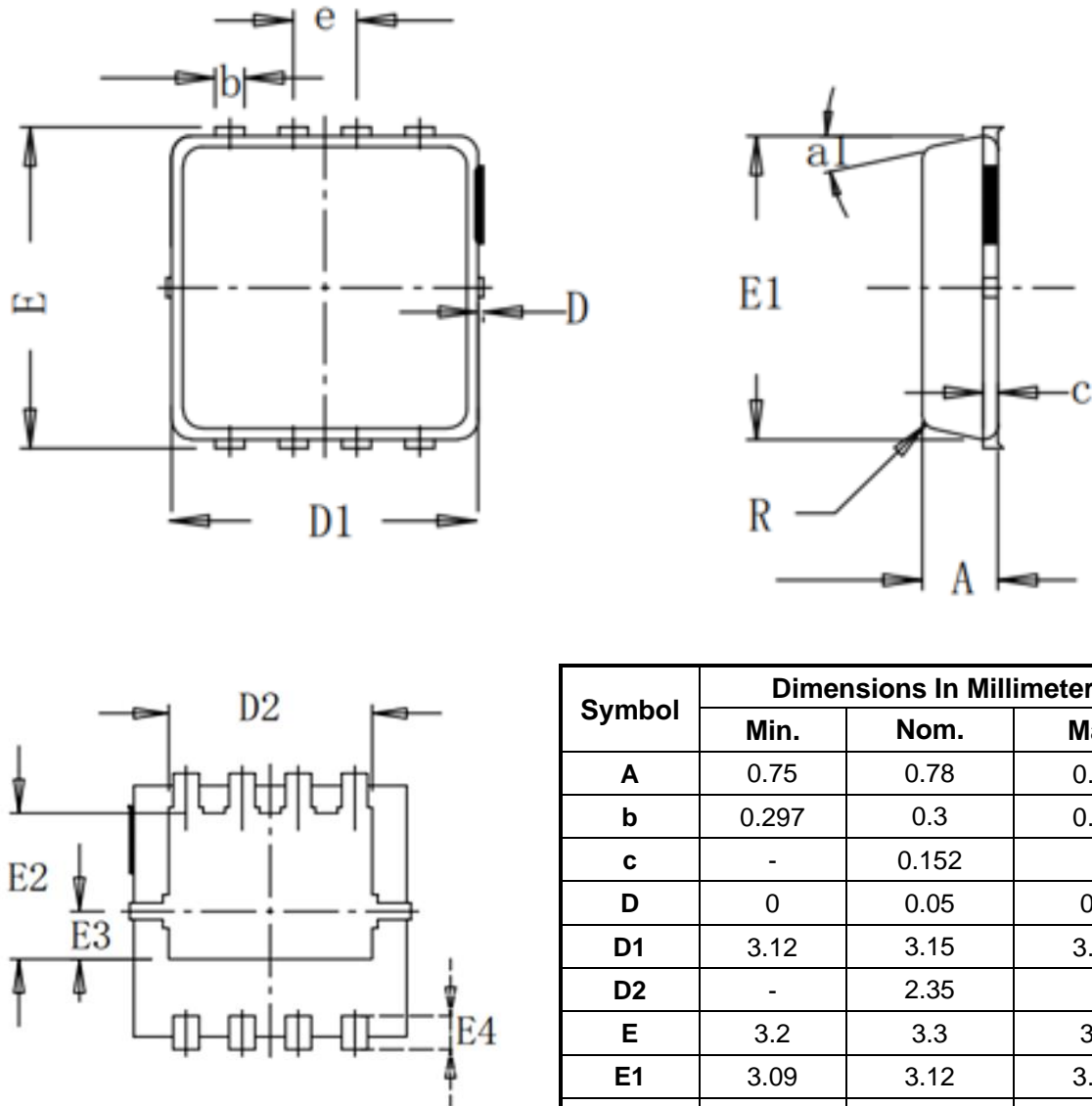


On-Resistance vs. Junction Temperature



Safe Operating Area, Junction-to-Ambient

➤ Package Information



Symbol	Dimensions In Millimeters		
	Min.	Nom.	Max.
A	0.75	0.78	0.81
b	0.297	0.3	0.35
c	-	0.152	-
D	0	0.05	0.1
D1	3.12	3.15	3.18
D2	-	2.35	-
E	3.2	3.3	3.4
E1	3.09	3.12	3.15
E2	-	1.75	-
E3	-	0.575	-
E4	-	0.4	-
R	-	0.15	-
e	0.65BSC		
a1°	-	12°	-



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